AKSHAY C J

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Executive summary

- Result oriented **Design Engineering professional, having 5 years of Experience in Electro-Mechanical Design**.
- Experience in **Designing Electro-Mechanical Enclosure for Industrial and Automotive Applications.**
- Proficiency in **SolidWorks**, **CATIA V5 and AutoCAD 2D design softwares.**
- Worked on **Plastic Injection molding, Metal Die Casting, 3D printing and prototyping, Draft Analysis, material selection and detail 2d drawing.**
- Comprehensive knowledge of different **manufacturing process, GD&T and drafting**.
- Involvement in **End-to-End product development**.

Experience Details

Presently Working in **iWave Systems Technologies Pvt Ltd as Senior Design Engineer** from 02.11.2017.

Project summary

Project: On-Board Diagnostics (OBD) for Automobile Industry
Key Features: Prototype 3d printing, injection molding, snap fit enclosure.

- Design of prototype for SLA 3d printing.
- Vacuum casting ABS plastic enclosure for small quantity order to meet customer timelines.
- Design of press fit enclosure with snaps. Easy assembly and disassembly without the help of tools.
- Selection of standard IM surface finish for aesthetics and functional application.
- Creation of 2D drawings for designed parts and assemblies.
- Preparation of inspection report to minimize the rejection rate in production batches.

Project: Telematics Rugged IP Rated Plastic Enclosure Design
Key Features: Injection molding, draft analysis, rugged IP rated design, IP rated testing, vibration testing, shock testing, thermal conduction plastic material selection, and detail 2d drawing.

- Draft, develop and design a rugged IP rated plastic injection molded enclosure.
- Selection of IP rated rugged automotive connector and antenna RF connectors.

- Design of sliding PCB to facilitate easy assembly of product.
- Prototype development with 3d printed enclosure to verify design functionality.
- Work closely with injection molding vendor to provide alternatives to DFM issues faced by the vendor.
- Design of rubber gasket for IP rating of the enclosure. Design of rubber gasket in a way where adhesive is not necessary to stick to the panel.
- Exploration of alternative gasketing option in FIP (Form in place) gasket.
- Creation of 2d drawings of the design parts and assembly instruction document.
- Perform dust, water jet, immersion, vibration and shock test on the enclosure.
- Have through knowledge on environmental testing methods and specifications.

Project: Human Machine Interface (HMI) Aluminum Die Casting Enclosure Design
Key Features: Die Casting, draft analysis, modular back case, integrated heat sink design, material selection, membrane keypad, panel mounting gasket, M12 connectors, IP rated rugged metal enclosures, different fixing methods.

- Draft, develop and design a 7 -inch, 10.1-inch and 12.-inch complete fan less HMI's.
- Design of flush mount display with front fascia protected from environmental ingress (IP rating).
- Design of modular back cover which could be used for different LCD sizes.
- Integrated heat sink design with back cover. Performed experimental thermal testing to verify the heat sink fins.
- Selection of thermal interface material for efficient heat transfer from heat dissipating modules present on circuit board.
- Use of membrane keypad in the product for physical tactile external keys. Through knowledge on membrane keypads.
- Calculations on the compression rate of silicone rubber gasket.
- Selection of M12 connectors for complete IP rated enclosure design. Finding alternate low cost M12 connectors to support low budget customers.
- Performed internal splash and immersion water testing to validate the enclosure protection.
- Detailed assembly instruction manual for assembly and production house.

Project: Sheet Metal Design for Control Panel Cabinet
Key Features: Injection molding, draft analysis, integrated heat sink design, material selection, and detail 2d drawing.

- Design of control panel cabinet for railways application.

- Design using concealed hinges and quarter turn lock for ease of maintenance and security respectively.
- Panel mount of 10.1-inch HMI on the front door of cabinet.
- Selection and testing of FIP gasket material for ingress protection.
- Fixture of wireless read writer on control panel front door.
- Prototyping and improvement of defects for the final production units.
- Detailed 2D drawing for manufacturing unit

Education

COURSE	SPECIALIZATION	INSTITUTION	BOARD	YEAR	PERCENTAGE
B. E	Mechanical Engineering	Reva University, Bangalore	VTU	2017	69.23%
12^{th}	PCMB	Jawahar Navodaya Vidyalaya, Gadag	CBSE	2013	80%
10^{th}	S.S.L.C	Jawahar Navodaya Vidyalaya, Gadag	CBSE	2011	9.2(CGPA)

Personal details

Name: AKSHAY C JANGANNAVAR
Father's Name: CHANNABASAPPA
Date of Birth: 29/03/1995
Nationality: Indian
Marital Status: Unmarried
Languages: English, Kannada & Hindi

Declaration

I hereby declare that the above-mentioned information is correct to the best of my knowledge.

Akshay C Jangannavar
Bangalore. Date: